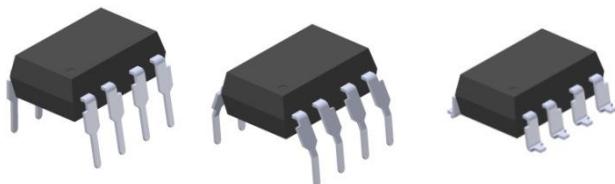


## 8 PIN DIP HIGH SPEED 1Mbit/s TRANSISTOR PHOTOCOUPLED 6N135 6N136 EL450X Series

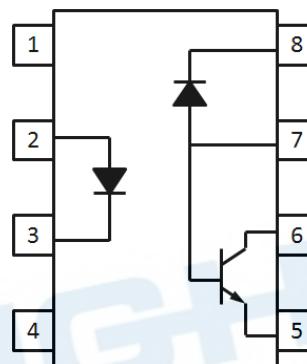


### Features

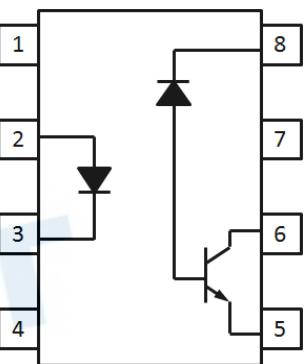
- High speed 1Mbit/s
- High isolation voltage between input and output ( $V_{iso}=5000$  Vrms )
- Guaranteed performance from 0°C to 70°C
- Wide operating temperature range of -55°C to 100°C
- Pb free and RoHS compliant
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

Schematic

6N135 / 6N136



EL4502 / EL4503



Pin Configuration

1. No Connection
2. Anode
3. Cathode
4. No Connection
5. Gnd
6.  $V_{out}$
7.  $V_B$
8.  $V_{CC}$

Pin Configuration

1. No Connection
2. Anode
3. Cathode
4. No Connection
5. Gnd
6.  $V_{out}$
7. No Connection
8.  $V_{CC}$

### Description

The 6N135, 6N136, EL4502 and EL4503 devices each consist of an infrared emitting diode, optically coupled to a high speed photo detector transistor. A separate connection for the photodiode bias and output-transistor collector increase the speed by several orders of magnitude over conventional phototransistor photo couplers by reducing the base-collector capacitance of the input transistor. The devices are packaged in an 8-pin DIP package and available in wide-lead spacing and SMD option

### Applications

- Line receivers
- Telecommunication equipments
- Power transistor isolation in motor drives
- Replacement for low speed phototransistor photo couplers
- Feedback loop in switch-mode power supplies
- Home appliances
- High speed logic ground isolation

**Absolute Maximum Ratings (Ta=25°C)**

	Parameter	Symbol	Rating	Unit
Input	Forward current	$I_F$	25	mA
	Peak forward current (50% duty, 1ms P.W)	$I_{FP}$	50	mA
	Peak transient current (≤1μs P.W,300pps)	$I_{Ftrans}$	1	A
	Reverse voltage	$V_R$	5	V
Output	Power dissipation	$P_{IN}$	45	mW
	Power dissipation	$P_o$	100	mW
	Emitter-Base reverse voltage 6N135 6N136	$V_{EBR}$	5	V
	Base current 6N135 6N136	$I_B$	5	mA
	Average Output current	$I_{O(AVG)}$	8	mA
	Peak Output current	$I_{O(PK)}$	16	mA
	Output voltage	$V_o$	-0.5 to 20	V
	Supply voltage	$V_{cc}$	-0.5 to 30	V
Total Power Dissipation		$P_{TOT}$	200	mW
Isolation Voltage*1		$V_{ISO}$	5000	Vrms
Operating Temperature		$T_{OPR}$	-55 to 100	°C
Storage Temperature		$T_{STG}$	-55 to 125	°C
Soldering Temperature*2		$T_{SOL}$	260	°C

## Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3, 4 are shorted together, and pins 5, 6, 7, 8 are shorted together.

\*2 For 10 seconds

**Electrical Characteristics (T<sub>A</sub>=0 to 70°C unless specified otherwise)****Input**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V <sub>F</sub>	-	1.45	1.8	V	I <sub>F</sub> =16mA
Reverse Voltage	V <sub>R</sub>	5.0	-	-	V	I <sub>R</sub> = 10µA
Temperature coefficient of forward voltage	ΔV <sub>F</sub> /ΔT <sub>A</sub>	-	-1.9	-	mV/°C	I <sub>F</sub> =16mA

**Output**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Logic High Output Current	I <sub>OH</sub>	-	0.001	0.5	µA	I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =5.5V, T <sub>A</sub> =25°C
		-	0.01	1		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =15V, T <sub>A</sub> =25°C
		-	-	50		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =15V
Logic Low Supply Current	I <sub>CCL</sub>	-	140	200	µA	I <sub>F</sub> =16mA, V <sub>O</sub> =Open, V <sub>CC</sub> =15V
Logic High Supply Current	I <sub>CCH</sub>	-	0.01	1	µA	I <sub>F</sub> =0mA, V <sub>O</sub> =Open, V <sub>CC</sub> =15V, T <sub>A</sub> =25°C
		-	-	2		I <sub>F</sub> =0mA, V <sub>O</sub> =Open, V <sub>CC</sub> =15V

**Transfer Characteristics (T<sub>A</sub>=0 to 70°C unless specified otherwise)**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer Ratio	CTR	6N135	7	-	50	I <sub>F</sub> = 16mA, V <sub>O</sub> = 0.4V, V <sub>CC</sub> =4.5V, T <sub>A</sub> =25°C
		6N136	19	-	50	
		EL4502			%	
Current Transfer Ratio	CTR	EL4503				I <sub>F</sub> = 16mA, V <sub>O</sub> = 0.5V, V <sub>CC</sub> =4.5V
		6N135	5	-	-	
		6N136	15	-	-	
Logic Low Output Voltage	V <sub>OL</sub>	EL4502				I <sub>F</sub> = 16mA, I <sub>O</sub> = 1.1mA, V <sub>CC</sub> =4.5V, T <sub>A</sub> =25°C
		EL4503				
		6N135	-	0.18	0.4	
Logic Low Output Voltage	V <sub>OL</sub>	6N136	-	0.25	0.4	I <sub>F</sub> = 16mA, I <sub>O</sub> = 3mA, V <sub>CC</sub> =4.5V, T <sub>A</sub> =25°C
		EL4502				
		EL4503				
Logic Low Output Voltage	V <sub>OL</sub>	6N135	-	-	0.5	I <sub>F</sub> = 16mA, I <sub>O</sub> = 0.8mA, V <sub>CC</sub> =4.5V
		6N136	-	-	0.5	
		EL4502				
Logic Low Output Voltage	V <sub>OL</sub>	EL4503				
		6N135				
		6N136				
Logic Low Output Voltage	V <sub>OL</sub>	EL4502				
		EL4503				
		6N135				

## Switching Characteristics (TA=0 to 70°C unless specified otherwise, IF=16mA, Vcc=5V)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Propagation Delay Time to Logic Low (Fig.8)	6N135	-	0.35	1.5	μs	R <sub>L</sub> = 4.1KΩ, TA=25°C
		-	-	2.0		R <sub>L</sub> =4.1KΩ
		-	0.35	0.8		R <sub>L</sub> =1.9KΩ, TA=25°C
		-	-	1.0		R <sub>L</sub> =1.9KΩ
Propagation Delay Time to Logic High (Fig.8)	6N135	-	0.5	1.5	μs	R <sub>L</sub> = 4.1KΩ, TA=25°C
		-	-	2.0		R <sub>L</sub> =4.1KΩ
		-	0.3	0.8		R <sub>L</sub> = 1.9KΩ, TA=25°C
		-	-	1.0		R <sub>L</sub> =1.9KΩ
Common Mode Transient Immunity at Logic High (Fig.9)* <sup>3</sup>	6N135	1,000	-	-	V/μs	I <sub>F</sub> = 0mA , V <sub>CM</sub> =10Vp-p, R <sub>L</sub> =4.1KΩ, TA = 25°C
		1,000	-	-		I <sub>F</sub> = 0mA , V <sub>CM</sub> =10Vp-p, R <sub>L</sub> =1.9KΩ, TA = 25°C
		15000	20000	-		I <sub>F</sub> = 0mA , V <sub>CM</sub> =1500Vp-p, R <sub>L</sub> =1.9KΩ, TA = 25°C
		15000	20000	-		I <sub>F</sub> = 16mA , V <sub>CM</sub> =10Vp-p, R <sub>L</sub> =4.1KΩ, TA = 25°C
Common Mode Transient Immunity at Logic Low (Fig.9)* <sup>3</sup>	6N135	1,000	-	-	V/μs	I <sub>F</sub> = 16mA , V <sub>CM</sub> =10Vp-p, R <sub>L</sub> =1.9KΩ, TA=25°C
		1,000	-	-		I <sub>F</sub> = 16mA , V <sub>CM</sub> =1500Vp-p, R <sub>L</sub> =1.9KΩ, TA = 25°C
		15000	20000	-		I <sub>F</sub> = 16mA , V <sub>CM</sub> = 1500Vp-p, R <sub>L</sub> = 1.9KΩ, TA = 25°C
		15000	20000	-		I <sub>F</sub> = 16mA , V <sub>CM</sub> = 1500Vp-p, R <sub>L</sub> = 1.9KΩ, TA = 25°C

\* Typical values at T<sub>a</sub> = 25°C

## Typical Electro-Optical Characteristics Curves

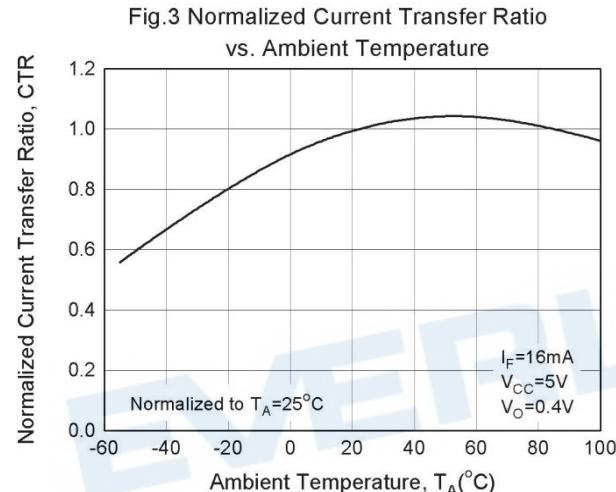
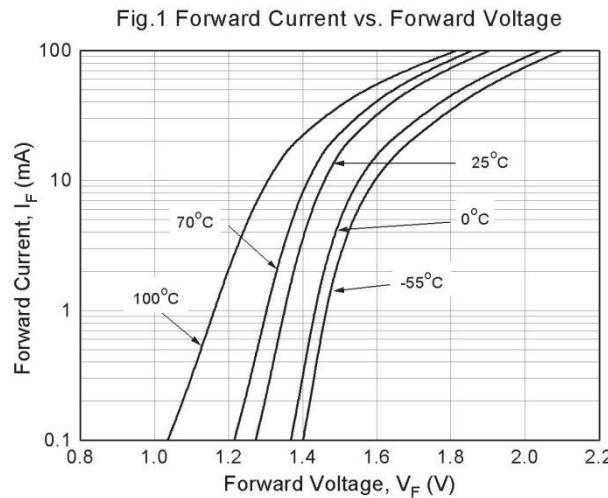


Fig.5 Logic High Output Current vs. Temperature

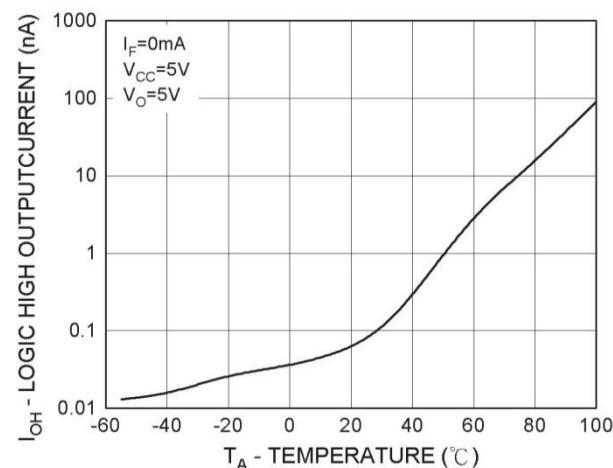


Fig.2 Normalized Current Transfer Ratio vs. Forward Current

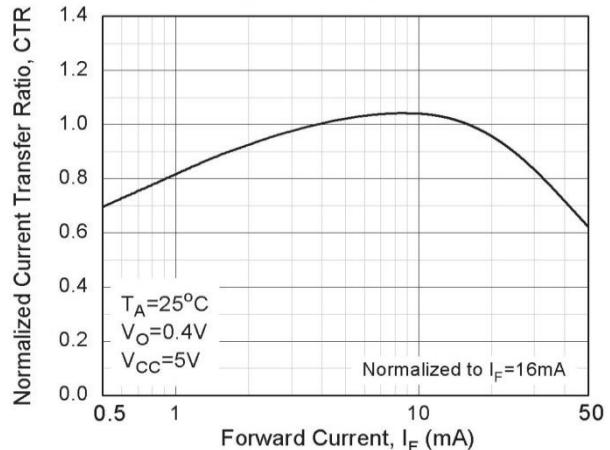


Fig.4 Output Current vs Output Voltage

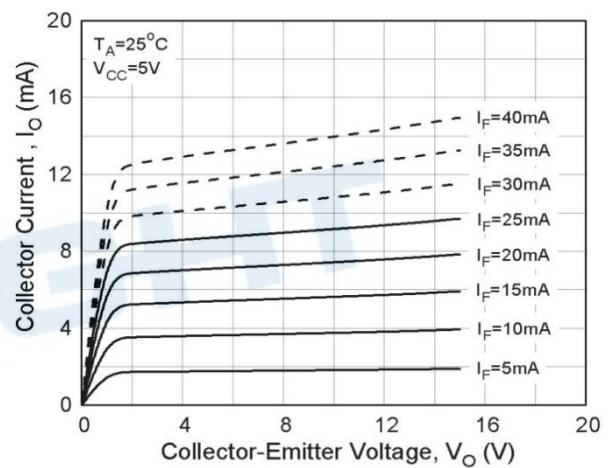


Fig.6 Propagation Delay vs. Load Resistance

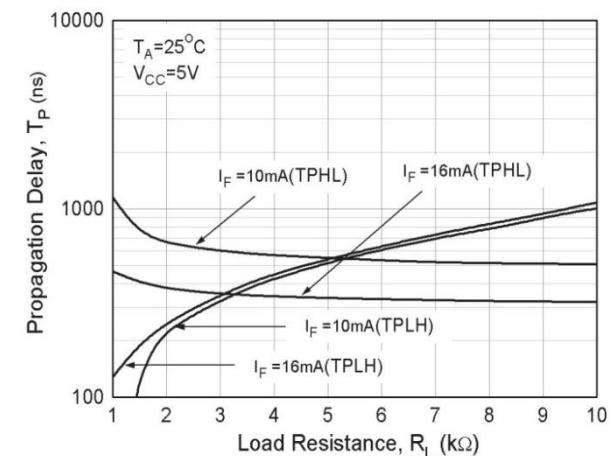


Fig.7 Propagation Delay vs. Temperature

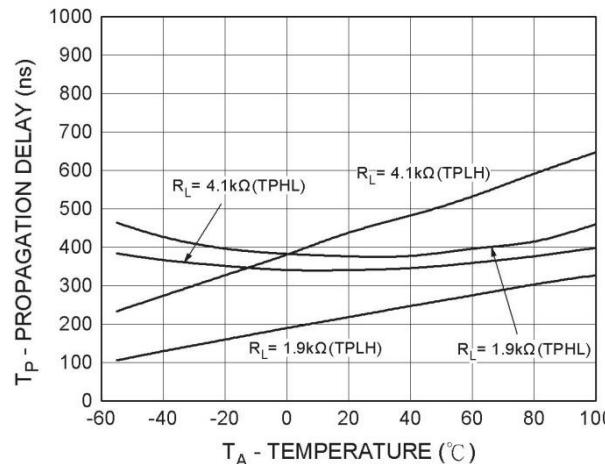


Figure 8 Switching Time Test Circuit &amp; Waveform

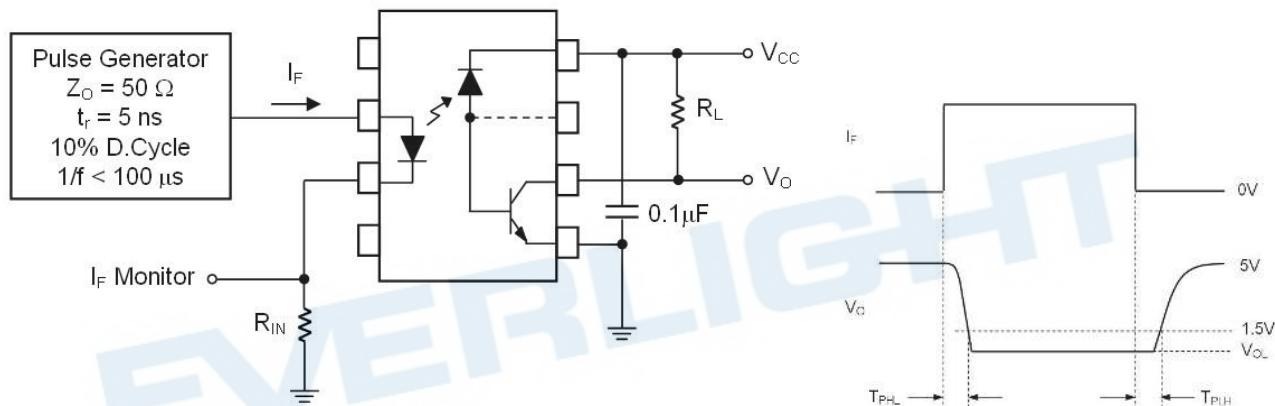
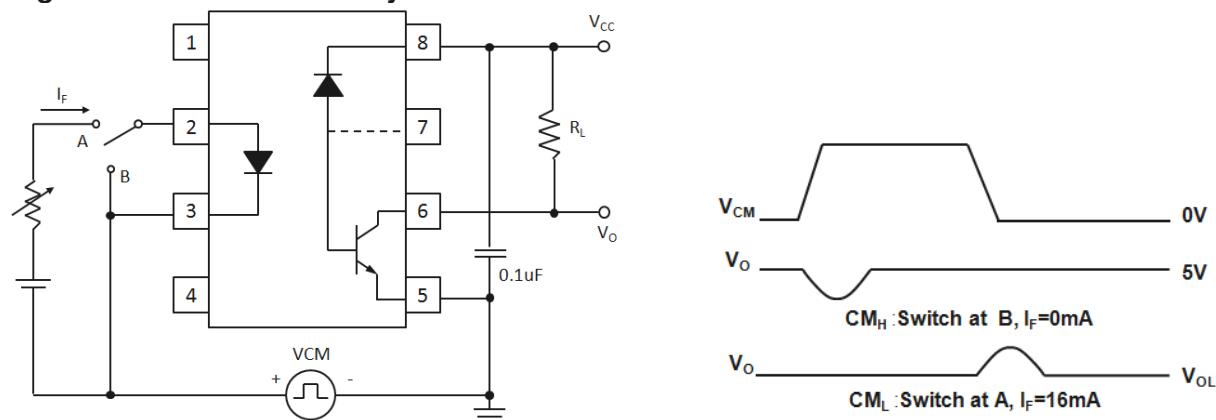


Figure 9 Transient Immunity Test Circuit &amp; Waveform

**Note:**

\*3 Common mode transient immunity in logic high level is the maximum tolerable (positive)  $dV_{CM}/dt$  on the leading edge of the common mode pulse signal  $V_{CM}$ , to assure that the output will remain in a logic high state (i.e.,  $V_O > 2.0V$ ).

Common mode transient immunity in logic low level is the maximum tolerable (negative)  $dV_{CM}/dt$  on the trailing edge of the common mode pulse signal,  $V_{CM}$ , to assure that the output will remain in a logic low state (i.e.,  $V_O < 0.8V$ ).

## Order Information

### Part Number

**6N13XY(Z)-V**

or

**EL450XY(Z)-V**

### Note

X = Part No. (X = 5 or 6) for 6N series; (X=2 or 3) for EL45 series

Y = Lead form option (S, S1, M or none)

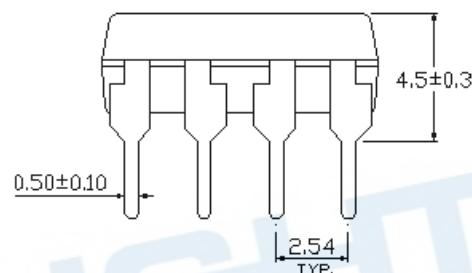
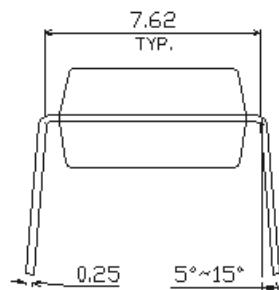
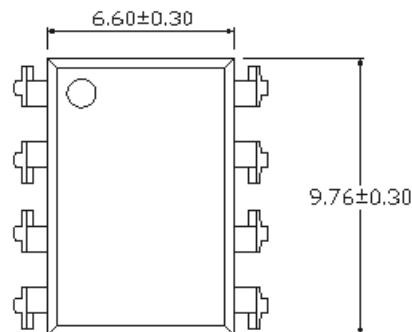
Z = Tape and reel option (TA, TB or none)

V = VDE (optional)

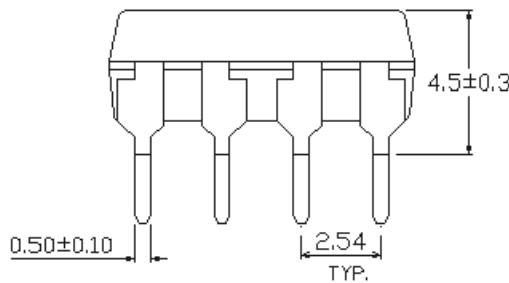
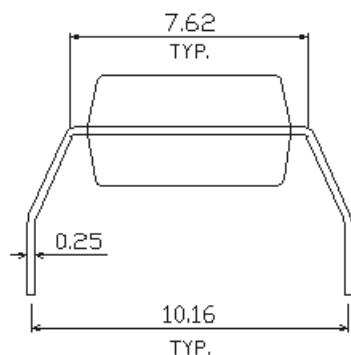
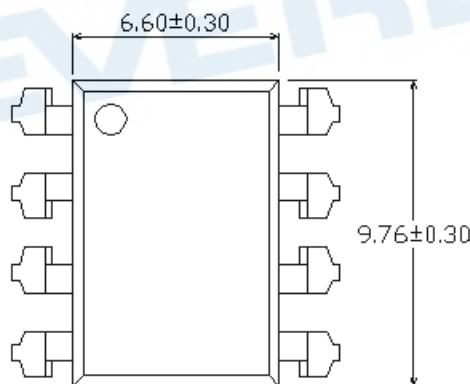
Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
M	Wide lead bend (0.4 inch spacing)	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

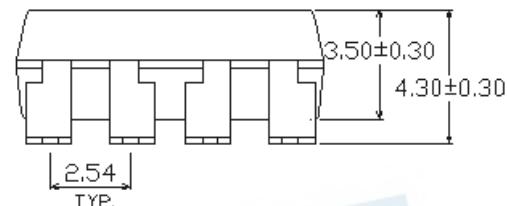
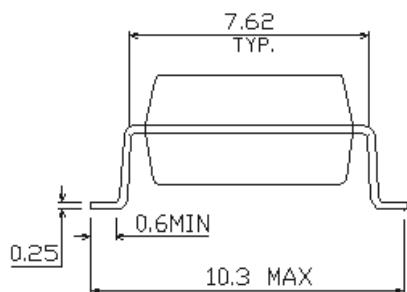
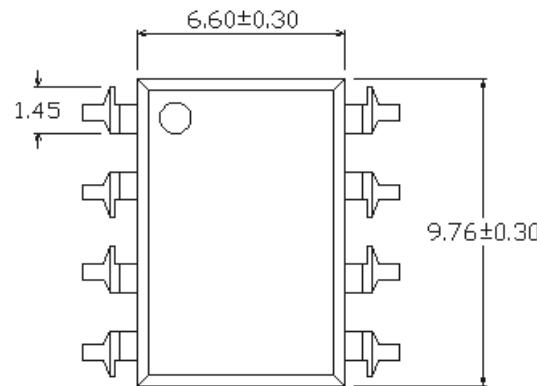
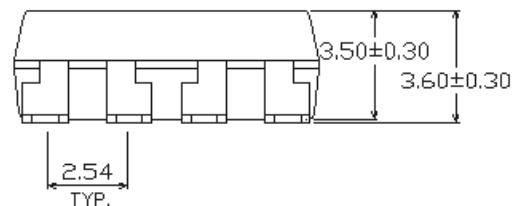
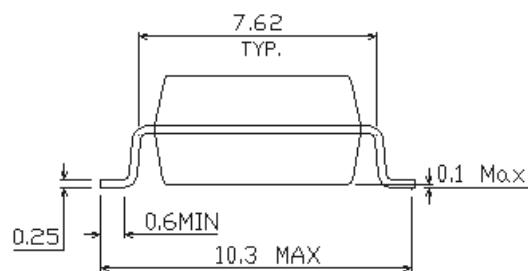
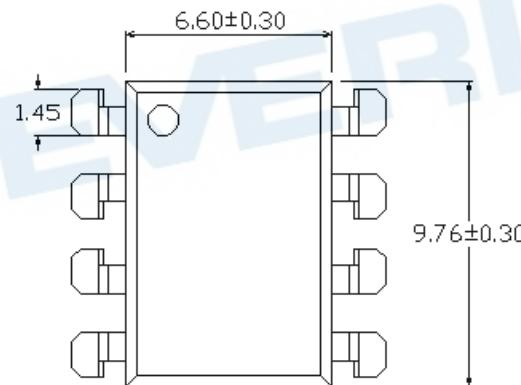
## Package Dimension (Dimensions in mm)

### Standard DIP Type

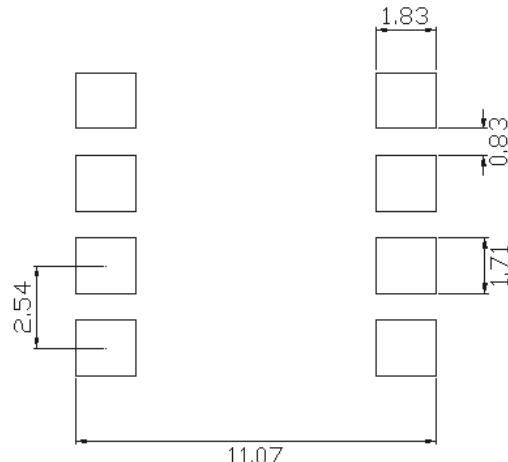


### Option M Type



**Option S Type****Option S1 Type**

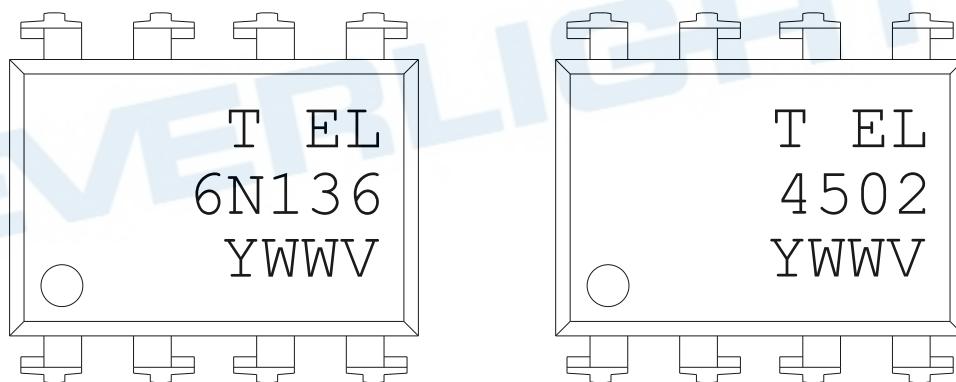
## Recommended pad layout for surface mount leadform



Notes.

Suggested pad dimension is just for reference only.  
Please modify the pad dimension based on individual need.

## Device Marking

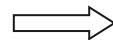
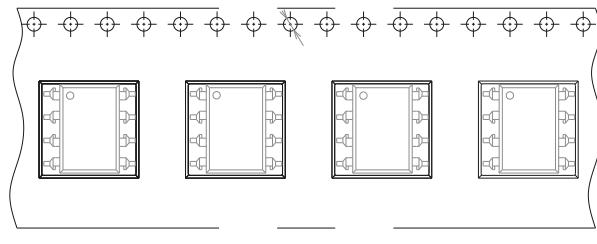


## Notes

T	denotes Factory No code : made in China T : made in Taiwan
EL	denotes EVERLIGHT
4502	denotes Device Number
6N136	denotes Device Number
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

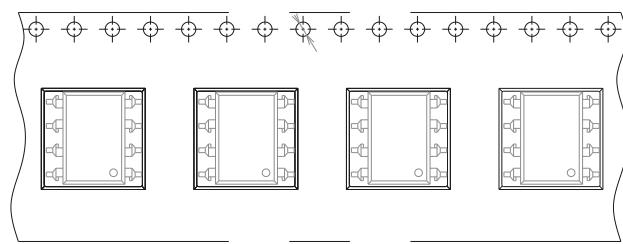
## Tape & Reel Packing Specifications

### Option TA



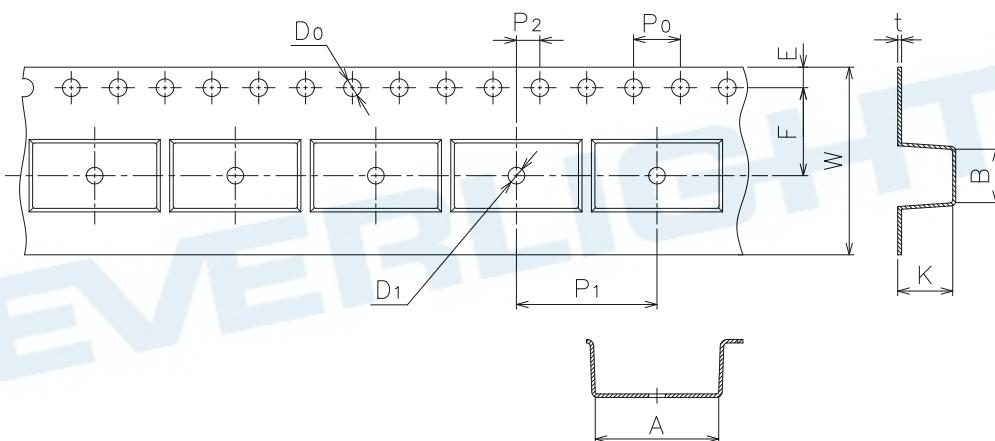
Direction of feed from reel

### Option TB



Direction of feed from reel

## Tape dimensions

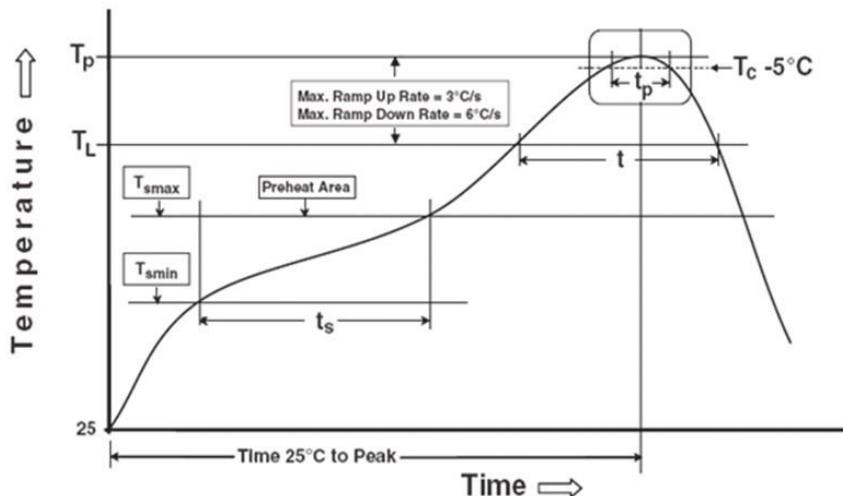


Dimension No.	<b>A</b>	<b>B</b>	<b>D<sub>0</sub></b>	<b>D<sub>1</sub></b>	<b>E</b>	<b>F</b>
Dimension(mm)	$10.4 \pm 0.1$	$10.0 \pm 0.1$	$1.5 + 0.1 / -0$	$1.5 \pm 0.25$	$1.75 \pm 0.1$	$7.5 \pm 0.1$
Dimension No.	<b>P<sub>0</sub></b>	<b>P<sub>1</sub></b>	<b>P<sub>2</sub></b>	<b>t</b>	<b>W</b>	<b>K</b>
Dimension(mm)	$4.0 \pm 0.1$	$12.0 \pm 0.1$	$2.0 \pm 0.05$	$0.4 \pm 0.05$	$16.0 \pm 0.3$	$4.5 \pm 0.1$

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

## DISCLAIMER

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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